Industry's Most Efficient Nano Power Harvesting Solutions

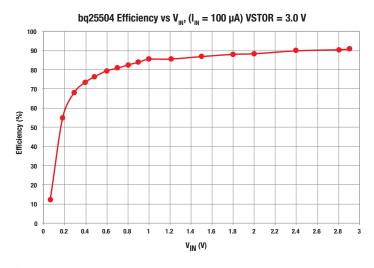
Extract and manage µW to mW



Industry's Most Efficient Nano Power Harvesting Solutions

Featured Energy Harvesting ICs

Product	Description
bq25505	Ultra-low power boost converter with battery management and autonomous power path multi-plexing
bq25504	Ultra-low power boost converter with battery management
bq25570	Ultra-low power boost converter with battery management and buck output regulation
TPS62736/37	Ultra-low lq nano-buck regulators
bq25504EVM-674	Evaluation module for bq25504 ultra-low-power boost converter
TPS62736EVM-205	Evaluation module for TPS62736 programmable output ultra-low-power buck converter





bq25504

Ultra-low power boost converter with battery management

Key Features

- High-efficiency DC/DC boost converter/charger
- Programmable dynamic Maximum Power Point Tracking (MPPT) with cold start feature
- Flexible energy storage options
- · Battery charging and protection

bq25505

Ultra-low power boost converter with battery management and autonomous power path multi-plexing



Key Features

- High-efficiency DC/DC boost converter/charger with MPPT
- Autonomous multiplexing for primary and secondary power
- Flexible energy storage options
- Battery charging and protection

bq25570

Ultra-low power boost converter with battery management and buck output regulation

Nano Power Boost Charger

Key Features

- High efficiency DC/DC boost converter/charger with built-in buck regulation
- MPPT with cold start feature
- Flexible energy storage options
- Battery charging and protection

TPS62736/37

Programmable output Nano-Power buck converters with 50 mA load capability



Key Features

- High-efficiency (>90% at 15 μA) buck regulators with programmable output regulation
- Ultra-low active current (350 nA)
- Pass mode option
- Two power-off states, including Input Power Good indication

For more information, visit ti.com/energyharvestinglCs



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